



## Product/Process Change Notice - PCN 09\_0050 Rev. -

Analog Devices, Inc. Three Technology Way Norwood, Massachusetts 02062-9106

This notice is to inform you of a change that will be made to certain ADI products (see Material Report). Any issues with this PCN or requirements to qualify the change (additional data or samples) must be sent to ADI within 30 days of receiving this notification. The information contained within this PCN is considered proprietary and should not be shared outside of your company. ADI contact information is listed below.

**PCN Title:** Assembly Site Transfer of SOT89 Package to Cirtek Electronics Corporation, Philippines and Change of Molding Compound

**Publication Date:** 01-Apr-2009

**Samples Available Date:** 01-May-2009

**Effectivity Date:** 28-Jun-2009 *(the earliest date that a customer could expect to receive changed material)*

### Description Of Change

This is a notification that ADI is qualifying Cirtek Electronics Corporation, Philippines, as an Assembly Site for SOT89 package.

Upon successful completion of qualification, ADI will be transferring SOT89 assembly processes from Jiangsu Changjiang Electronics Technology Co. Ltd. (JCET), Jiangsu, China to Cirtek Electronics Corporation, Laguna, Philippines.

Molding compound will be changing from E'dale ELL-2K1 to Sumitomo G600.

### Reason For Change

SOT89 assembly process qualification of Cirtek Electronics Corporation will enable ADI to increase manufacturing efficiency across ADI subcontractor assembly sites. This increased efficiency will support customer requirement for a reliable assembly supply chain. ADI is committed in making sure that the necessary manufacturing capability and capacity are in place in order to consistently meet customer requirements.

Molding compound change to Sumitomo G600 will align ADI SOT89 package with the list of "Green Materials" required by the majority of our customer base.

### Impact of the change (positive or negative) on fit, form, function & reliability

Device quality, reliability, function, and performance, as specified on Product Data Sheets, will not be affected by this change.

ADI SOT89 Package Outline Drawings (POD) is provided in this PCN for your reference. The assembly site transfer will not affect package dimensions and will remain compliant to the published ADI SOT89 Package Outline Drawings (POD).

Molding compound will be changing from E'dale ELL-2K1 to Sumitomo G600 in order to align with the list of "Green Materials" as required by the majority of our customer base. There will be no change in Die Attach and Substrate/Leadframe materials.

### Product Identification *(this section will describe how to identify the changed material)*

SOT89 package with date code 0927.

### Summary of Supporting Information

Qualification will be performed as per Analog Devices specification ADI0012, Procedure for Qualification of New or Revised Processes or Products. See attached qualification plan.

### Supporting Documents

**Attachment 1:** ADI\_PCN\_09\_0050\_Rev\_-\_09\_0050\_Qual\_Summary.xls

For questions on this PCN, send email to the regional contacts below or contact your local ADI sales representative

**Americas:** PCN\_Americas@analog.com

**Europe:** PCN\_Europe@analog.com

**Japan:** PCN\_Japan@analog.com

**Rest of Asia:** PCN\_ROA@analog.com

**Appendix A - Affected ADI Models**

**Added Parts On This Revision - Product Family / Model Number (2)**

ADL5320 / ADL5320ARKZ-R7

ADL5321 / ADL5321ARKZ-R7

**Appendix B - Revision History**

<b>Rev</b>	<b>Publish Date</b>	<b>Rev Description</b>
Rev. -	01-Apr-2009	Initial Release

Analog Devices, Inc.

DocId:677 Parent DocId:None